

REMARKS

Claims 1-17 are pending in the present application. Claims 1, 2 and 15 are herein amended. Claims 4-14 and 16-17 have been withdrawn from consideration. Support for the amendments is detailed below.

Applicants' Response to the Rejections under 35 U.S.C. §102

Claim 1 stands rejected under 35 U.S.C. 102(b) as being anticipated by **Nagatomi *et al.*** In response thereto applicants have amended claim 1 to more distinctly claim the subject matter regarded as the invention. Specifically, applicants have added the feature to claim 1 of the elastically deformable resin layer on an outer surface of the roller. Further, the roller of amended claim 1, while rolling, will absorb unevenness of the outer surface of the roller and unevenness of the surface of the film by elastic deformation of the elastically deformable resin layer. **Nagatomi *et al.*** does not teach this feature of amended claim 1.

Nagatomi *et al.* discloses a roller 15a equipped with a heater (15e). The heater 15c is provided to heat the roller (15a) to heat the pressure sensitive tape (4) while rolling on the pressure sensitive tape (4) covering the semiconductor substrate (3) so as to control adhesion of the pressure sensitive tape (4).

On the other hand, according to amended claim 1, the pressing roller 10 has the heater 11 inserted into a central portion of the roller main part 12, and an elastically deformable resin layer 13 is provided on the outer surface of the roller main part 12 so as to absorb unevenness of the outer surface of the roller main part 12, unevenness of the surface of the die-attachment film and unevenness of the principal surface of the semiconductor substrate. See specification, page 15, lines 34-37, page 17,

lines 2-5. Wherefore, applicants submit that not all the limitations of amended claim 1 are disclosed by **Nagatomi et al.** and respectfully request favorable reconsideration.

Applicants' Response to the Rejections under 35 U.S.C. §103

Claims 2 and 3 stand rejected under 35 U.S.C. 103(a) as being unpatentable over **Nagatomi et al.** in view of **Inada et al.** The **Nagatomi et al.** reference is silent as to the resin layer provided on the outer surface of the roller. As noted above, applicants have amended claim 1 to further include the features of the resin layer. Applicants respectfully submit that even if the combination of **Nagatomi et al.** and **Inada et al.** were made, the combined references would not result in the presently claimed invention. Specifically, neither reference teaches or suggests a resin layer which is capable of absorbing unevenness of the various surfaces.

The **Inada et al.** reference discloses a pressing roller (3) used for sticking the metallic foil (2) on the insulating tape (1). A Teflon or silicone film is formed on the outer surface of the pressing roller (3) so as to prevent adhesion of the adhesive applied onto the insulating tape (1). The Teflon or silicone film of the **Inada et al.** reference is provided only to prevent sticking of the adhesive.

Contrary, the elastically deformable resin layer of the present invention is provided to absorb unevenness in the pressure contact surfaces. Absorbing unevenness is particularly important when heat is applied from the processing roller to the film since unevenness of the surface generates uneven transmission of heat to the film, which may results in uneven lamination of the film.

The **Inada et al.** reference does not refer to or even suggest the problems caused by unevenness of the surface. The Teflon or silicone film of the **Inada et al.** reference does not have such a function to absorb unevenness in the pressure contact surfaces. The Teflon or silicone

film of the **Inada et al.** reference is a thin film coating, which does not provide elastic deformation. Accordingly, even if one combines the **Nagatomi et al.** reference and the **Inada et al.** reference to prevent sticking of the adhesive, the result would be a roller having a heater and a Teflon coating, which is not elastically deformable.

Thus, the **Inada et al.** reference does not remedy the deficiency of the **Nagatomi et al.** reference. Hence, applicants respectfully submit that amended claim 1 and claims 2 - 3 are not derivable from a combination of the **Nagatomi et al.** reference and the **Inada et al.** reference.

Claim 15 stands rejected under 35 U.S.C. 103(a) as being unpatentable over **Nagatomi et al.** in view of the admitted prior art. In response thereto, applicants have amended claim 15 to more distinctly claim the subject matter regarded as the invention. Specifically, claim 15 has been amended to include the features of an elastically deformable resin layer as discussed above in regard to amended claim 1. For the same reasons as discussed above in regard to amended claim 1, **Nagatomi et al.** does not teach each and every limitation of amended claim 15.

In view of the aforementioned amendments and accompanying remarks, Applicants submit that the claims, as herein amended, are in condition for allowance. Applicants request such action at an early date.


If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney to arrange for an interview to expedite the disposition of this case.

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Amendment under 37 C.F.R. §1.111
Amendment filed: July 6, 2006

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,
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